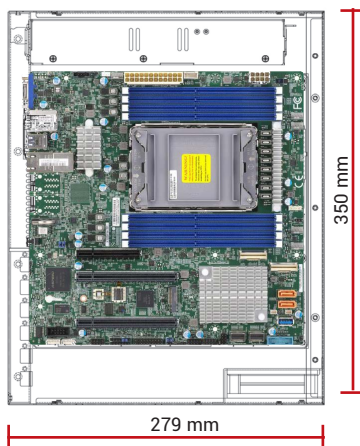


# Server Industriali

## Serie GO-B03 - Chassis Book-Mount per Motherboard



Server Industriale Book-Mount  
 Sei slot Full Height  
 Soluzione Front I/O  
 Configurato su richiesta  
 Burn in climatico su ogni apparato  
 Test Report di collaudo



### Chassis

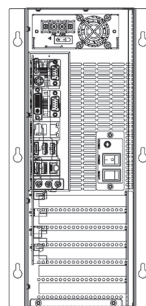
IP-365- Rev.2

Dimensioni	Chassis 350(A) x 124,9(L) x 279(P) mm
Montaggio	Book-Mount (staffe incluse) e Desktop
Materiale	Acciaio pre-zincato
Architettura	Motherboard 9.6" x 9.6", schede full height
Varianti	GO-B03: Chassis, con ventole PWM, colore nero.
Drives	Lettore Cfast opzionale
Ventilazione	2x ventole (60mm)
Led sul fronte	LED per Power On/Off e funzionalità HDD
Pulsanti	Power ON/OFF e System Reset
Fronte	I/O shield motherboard e bracket schede integrate
Alimentazione	Alimentatore 1U profondità - Power input frontale Versione AC o DC
Slot di espansione	6 slot Full Height
Colore	Nero o altri colori su richiesta
Shock	5G durata 11ms - EN 60068-2-27
Vibrazioni	10-150Hz: 1G - EN 60068-2-6
Umidità	10 - 95% non condensata
Temperatura	Operativa 0°C... +50°C Storage -20°C... +70°C

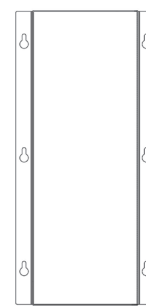
### Complementi

Storage	<ul style="list-style-type: none"> <li>• Disk on Module</li> <li>• Modulo CFAST estraibile</li> <li>• M.2 Interface: 1 PCI-E 3.0 x4 NVMe</li> <li>• M.2 Form Factor: 2242/2280</li> <li>• M.2 Key: M-Key</li> </ul>
Media	<ul style="list-style-type: none"> <li>• Tastiera beige/nera PS2/USB italiana/inglese</li> <li>• Mouse ottico PS2/USB</li> </ul>
Schede I/O	<ul style="list-style-type: none"> <li>• Ethernet Server Adapter</li> <li>• GPGPU / Schede Video</li> <li>• Schede Multi-Head</li> <li>• Schede I/O Analogiche e Digitali</li> <li>• Schede FPGA</li> <li>• Schede MULTISERIALI</li> <li>• Frame Grabber</li> <li>• MIL-1553 / ARINC 429 / ARINC 418</li> </ul>
Sistemi Operativi	<ul style="list-style-type: none"> <li>• Windows® versioni Enterprise / Embedded</li> <li>• Windows® versioni Server</li> <li>• Linux</li> </ul>

Fronte




Retro



124,9 mm

## Motherboard: MBD-X12SPM-TF

CPU/Cache	3rd Gen Intel® Xeon® Scalable processors Single Socket LGA-4189 (Socket P+) supported, CPU TDP supports Up to 205W TDP
Chipset	Intel® C621A
RAM	Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz; Up to 2TB 3DS ECC LRDIMM, DDR4-3200MHz
Network Controllers	Dual LAN with 10GBase-T with Intel® X550
Graphics	ASPEED AST2600 BMC
BIOS Features	<ul style="list-style-type: none"> <li>• ACPI 6.0</li> <li>• RTC (Real Time Clock) Wakeup</li> <li>• SMBIOS 3.0 or later</li> </ul>
Serial ATA	Intel® C621A controller for 10 SATA3 (6 Gbps) ports; RAID 0,1,5,10
LAN	2 RJ45 10GBase-T ports
USB	<ul style="list-style-type: none"> <li>• 6 USB 2.0 ports (2 rear + 4 via headers)</li> <li>• 5 USB 3.2 Gen1 ports (2 rear + 2 via headers + 1 Type A)</li> </ul>
Video	1 VGA port
Serial Port / Header	1 COM Port (1 header)
Expansion slots	Low profile boards: <ul style="list-style-type: none"> <li>• 2x PCI-E 4.0 x16</li> <li>• 1x PCI-E 4.0 x8</li> </ul>
Storage	<ul style="list-style-type: none"> <li>• M.2 Interface: 1x SATA/PCI-E 3.0 x4</li> <li>• M.2 Form Factor: 2280/22110</li> <li>• M.2 Key: M-Key</li> <li>• 1x CFAST estraibile</li> </ul>
I/O shield	<ul style="list-style-type: none"> <li>• 2x LAN</li> <li>• 4x USB</li> <li>• 1x VGA</li> <li>• 1x Dedicated IPMI LAN</li> <li>• UID Switch</li> </ul> 



## Alimentatori (profondità max 225 mm)



Z-P1H-5700G  
1U Single 700W

Output					
+3.3V	+5V	+12V	-5V	-12V	+5VSB
18A	18A	58A	-	0.5A	3A
Input 100 ~ 264VAC Full Range					
MTBF 204.972 h					
Dimensioni 100x40.5x225 mm					



Z-BN1H-5750V  
1U Single 750W 24VDC

Output					
+3.3V	+5V	+12V	-5V	-12V	+5VSB
25A	25A	60A	-	0.8A	3.5A
Input 18~36VDC					
MTBF 146.923 h					
Dimensioni 100x40.5x225 mm					

